

PRESSURIZED OXYGEN FOR EVALUATION OF MOLDING COMPOUND STABILITY IN SEMICONDUCTOR PACKAGING

Abstract of the Disclosure

A test environment and an associated method of testing and analyzing a semiconductor
5 package material containing a molding compound, for stability in a sustained oxygen
environment. Test samples are exposed to a pressurized gas containing oxygen, under elevated
temperature below the glass transition temperature of the molding compound. Control samples
are exposed to a pressurized inert gas under similar or more severe conditions of gas pressure,
temperature, and humidity. At least one characteristic common to the test samples and the
10 control samples is measured. A determination is made as to whether there exists at least one
significant difference between the at least one measured characteristic of the test samples and the
control samples.